

| REVISIONS | | | |
|-----------|------------------------------|------------|----------|
| REV | DESCRIPTION | DATE | APPROVED |
| A | ECO 2136072: Initial Release | 09/06/2013 | HPC |
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| | | DWN/CHK Paul Cleveland | DATE 02/14/2014 | CCA, NIRscan s241 DMD Board | | |
| | | SYS ENGR | | | | |
| | 0314CP | MANU | | | | |
| NHA | USED ON | QA | | SIZE A | DRAWING NO 2513468 | REV A |
| APPLICATION | | APVD | | SCALE NONE | SHEET 1 OF 5 | |

1. Scope

The purpose of this document is to establish the assembly requirements for the s241 DMD Board.

2. Related Documents

Texas Instruments Documents

| Dwg. Number | Document Name |
|-------------|-------------------------------------|
| 2513466 | 2513466a_NIRscan_s241_DMD_Board_ESD |
| 2513467 | 2513467a_NIRscan_s241_DMD_Board_PCB |

3. Notes

1. This PCB contains devices which are electrostatic discharge sensitive.
2. Mark the appropriate Manufacturing Serial Number (MSN) on the top of the PCB. Method and placement location optional.
3. Mark assembly number, assembly dash number and revision letter of CCA on the top of the PCB. Method and placement location optional.
4. Workmanship to be in accordance with ANSI/IPC-A-610B Class 2 and ANSI/J-STD-001A Class 2.
5. Equivalent or better part may be substituted.
6. Solder times and temperatures to be in conformance with PWB UL component recognition limits established for the particular board. The solder profile must also comply with the limits of all components on the PCB.
7. Components and processes should be lead-free and ROHS compliant.

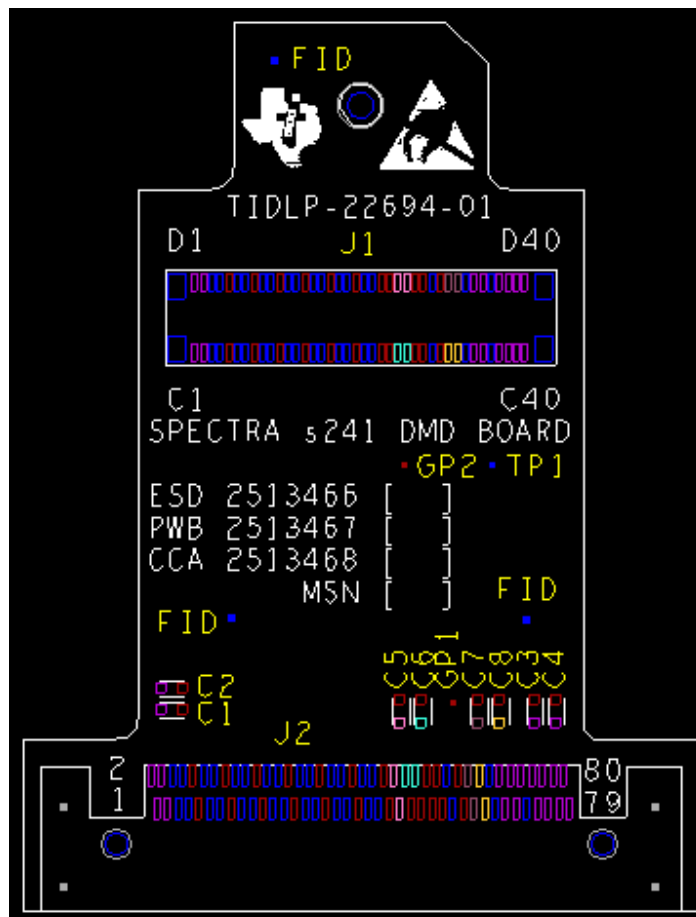
4. Bill of Material & Cross Reference List

Assembly bill of material and cross reference list are provided in attached spread sheet.

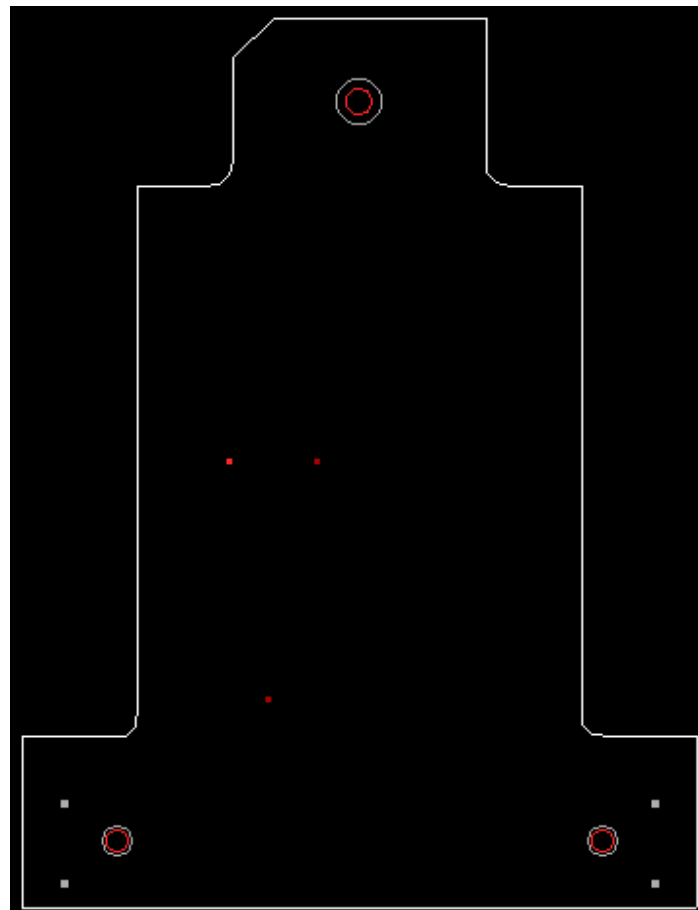
| Assembly Dash | Description | Material & Cross Reference List Spread Sheet |
|---------------|----------------|--|
| -1 | S241 DMD Board | 2513469a_NIRscan_s241_DMD_Board_BOM |

5. Assembly Diagrams

S241 DMD Board Top



S241 DMD Board Bottom



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